IN THE CLAIMS:

Please amend Claims 18 and 33 as follows:

18. (Amended) An electrode assembly comprising:

an electrode disk composed of a substantially pure material and having a

substantially uniform thickness; and

a support ring bonded about the periphery of one face of the disk, leaving the other

face substantially flat and free from protuberances, wherein the support ring

is composed of an electrically and thermally conductive material.

33. (Amended) A method for forming an electrode assembly including a support

ring and an electrode plate, said method comprising:

bonding the support ring about the periphery of the electrode plate at elevated

temperature, wherein the material of the [electrode plate] support ring has a

higher coefficient of thermal expansion than that of the electrode plate; and

allowing the bonded assembly to return to room temperature, whereby the

differential contraction imparts the desired stress.

STATEMENT UNDER 37 C.F.R § 1.178(b)

In accordance with the duty of notice as set forth in 37 C.F.R. § 1.178(b),

applicants hereby call to the attention of the Examiner a concurrent litigation involving

U.S. Patent No. 5,074,456. Specifically, the assignee of U.S. Patent No. 5,074,456, Lam

Research Corporation, is currently involved in a litigation in the United States District

Court for the Northern District of California. In the litigation, Lam Research Corporation

has alleged infringement of U.S. Patent No. 5,074,456.

Applicants respectfully request that action in this reissue application not be

suspended as it is the applicant's desire that this reissue application be examined at this

time.

In accordance with the duty of disclosure set forth in 37 C.F.R. § 1.56, applicants

hereby submit the following in conformance with the provisions of 37 C.F.R. §§ 1.97 and

1.98. Pursuant to 37 C.F.R. §1.98 a copy of the document listed below is enclosed.

Civil Docket for Case #: 3:03-cv-01335